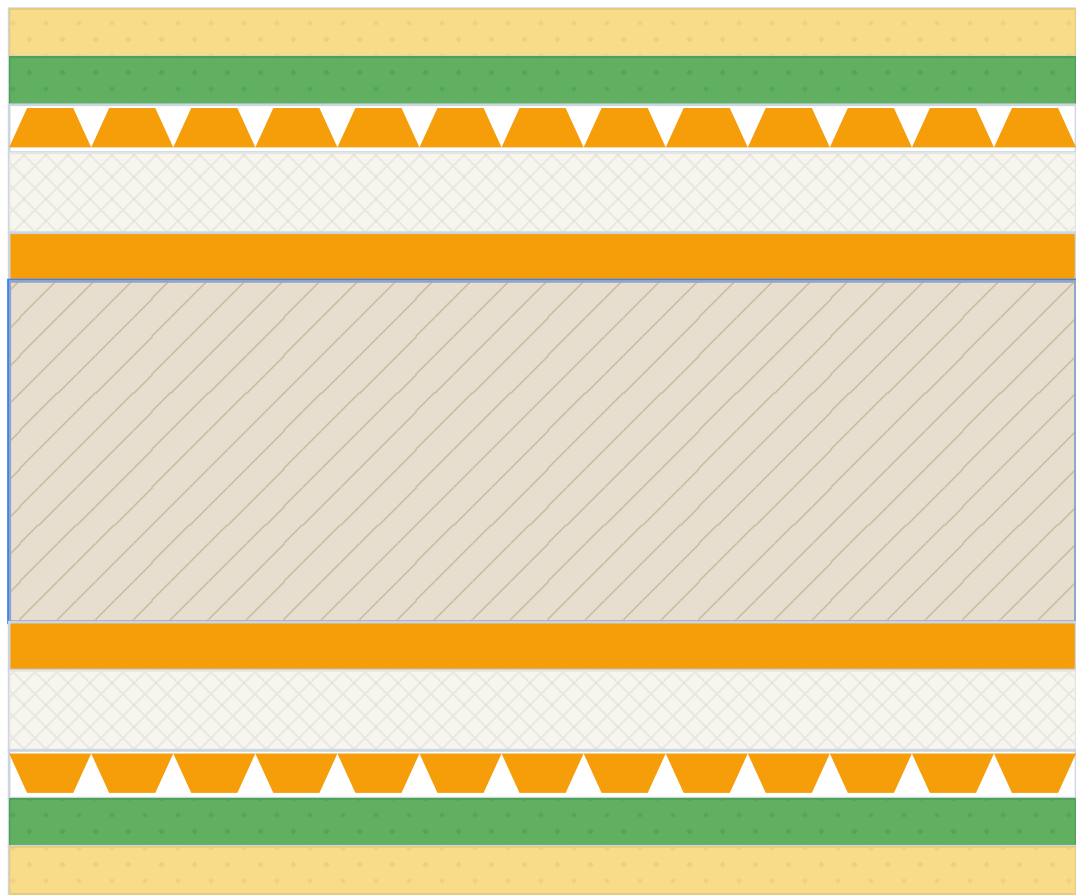


Top Surface Finish  
 Top Solder Mask  
**L1**  
 Prepreg  
**L2**  
 Core  
**L3**  
 Prepreg  
**L4**  
 Bottom Solder Mask  
 Bottom Surface Finish



**4L-2-7628-1-1-30**

Spec	Type	Base Thickness	Processed Thickness	RC	DK
ENIG		0.005			
		0.020			
	Signal	0.018	0.018		
FR4 · 7628	Prepreg	0.196	0.1715	43%	4.7
	Plane	0.035	0.035		
FR4	Core	1.43	1.43		4.6
	Plane	0.035	0.035		
FR4 · 7628	Prepreg	0.196	0.1715	43%	4.7
	Signal	0.018	0.018		
		0.020			
ENIG		0.005			

Thickness After Lamination: 1.879 mm

Finished PCB Thickness: 1.929 mm ±10%

Inner layer Residual copper ratio: 30%